Dual curable Adhesives using Thiol-based Chemistry

Kwang Su Seo, Ph.D.
Research Fellow
Chemence Inc

Camera modules used in consumer electronics continues to grow as electronic devices become both more mobile and increasingly, wearable. Market estimates predict that total revenue for compact camera module (CCM) will approach to nearly $50 billion (US dollar) by 2025. In addition, the number of camera's present on or in automotive vehicles will also increase significantly with automotive camera module volumes predicted to be broadly equivalent to the number used in mobile phone by 2025.

In this research, new dual cure adhesive for camera module assembly was developed using unique design of thiol-based chemistry. This technology was enable to generate high product stability at room temperature but have good product reactivity at temperature above 60 ^{o}C. In this presentation, new technology for dual curable adhesive chemistry will be discussed with physio-chemical properties.